

TK07H90A

Switching Regulator Applications

- Low drain-source ON resistance : $R_{DS(ON)} = 1.6\Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 5.0$ S (typ.)
- Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 720V$)
- Enhancement mode : $V_{th} = 2.0\sim 4.0$ V ($V_{DS} = 10$ V, $I_D = 1$ mA)

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	900	V
Drain-gate voltage ($R_{GS} = 20$ k Ω)		V_{DGR}	900	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	7	A
	Pulse (Note 1)	I_{DP}	21	A
Drain power dissipation ($T_c = 25^\circ C$)		P_D	150	W
Single-pulse avalanche energy (Note 2)		E_{AS}	491	mJ
Avalanche current		I_{AR}	7	A
Repetitive avalanche energy (Note 3)		E_{AR}	15	mJ
Channel temperature		T_{ch}	150	$^\circ C$
Storage temperature range		T_{stg}	-55~150	$^\circ C$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	0.833	$^\circ C / W$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	50	$^\circ C / W$

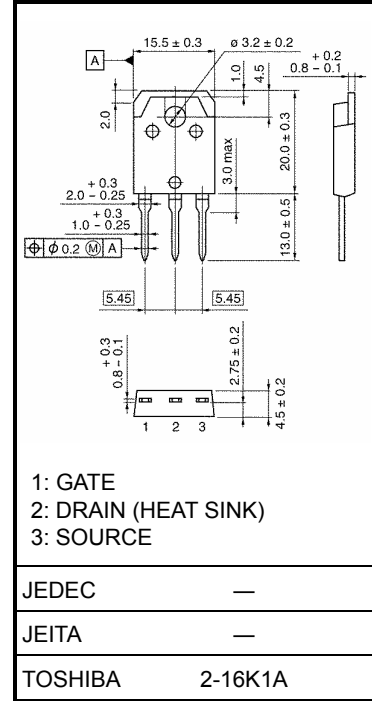
Note 1: Ensure that the channel temperature does not exceed $150^\circ C$.

Note 2: $V_{DD} = 90$ V, $T_{ch} = 25^\circ C$ (initial), $L = 18.4$ mH, $R_G = 25 \Omega$, $I_{AR} = 7$ A

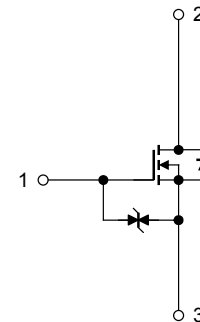
Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 3.8 g (typ.)



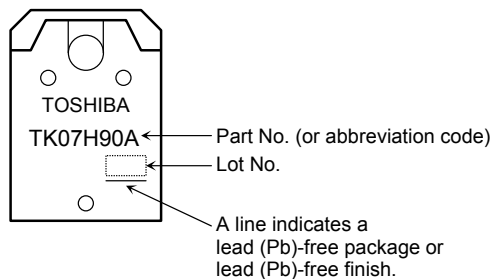
Electrical Characteristics (Ta = 25°C)

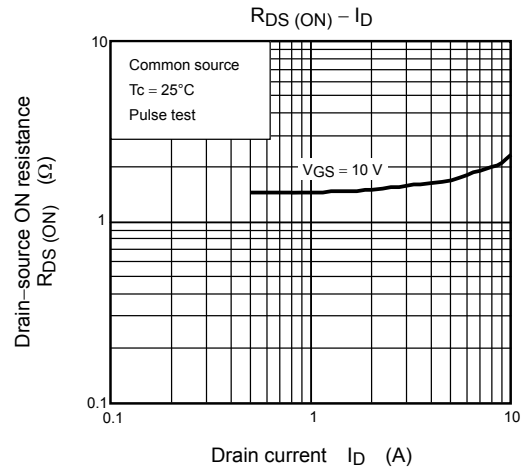
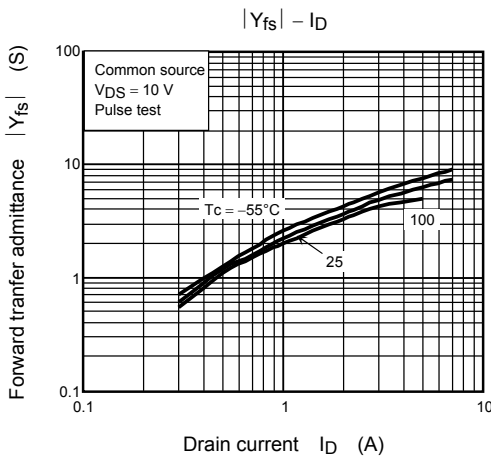
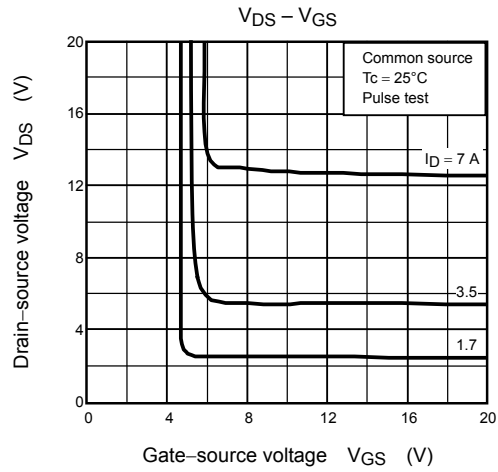
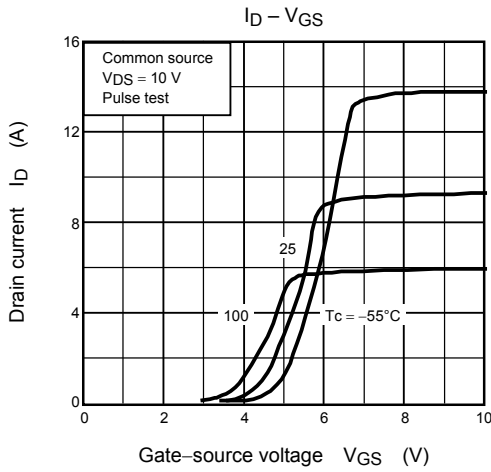
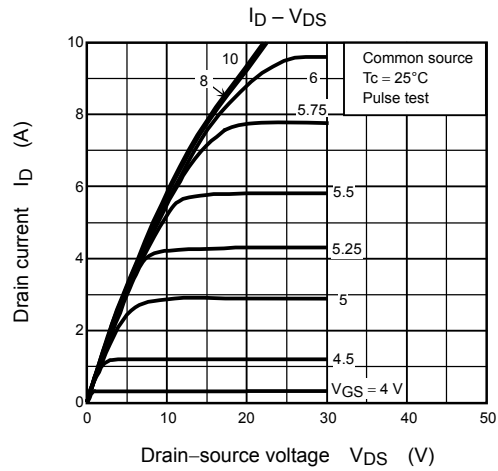
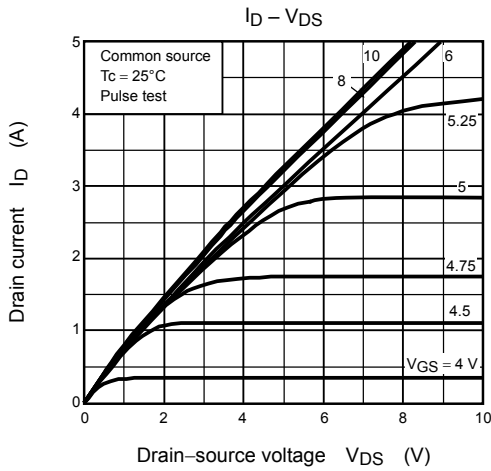
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I_{GSS}	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA	
Gate-source breakdown voltage	$V_{(BR)GSS}$	$I_G = \pm 10\ \mu\text{A}, V_{DS} = 0\text{ V}$	± 30	—	—	V	
Drain cutoff current	I_{DSS}	$V_{DS} = 720\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	900	—	—	V	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	2.0	—	4.0	V	
Drain-source ON resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 3.5\text{ A}$	—	1.6	2.0	Ω	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 3.5\text{ A}$	3.5	5.0	—	S	
Input capacitance	C_{iss}	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	1650	—	pF	
Reverse transfer capacitance	C_{rss}		—	30	—		
Output capacitance	C_{oss}		—	140	—		
Switching time	Rise time	t_r		—	50	—	ns
	Turn on time	t_{on}		—	90	—	
	Fall time	t_f		—	70	—	
	Turn off time	t_{off}		—	240	—	
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 400\text{ V}, V_{GS} = 10\text{ V}, I_D = 7\text{ A}$	—	45	—	nC	
Gate-source charge	Q_{gs}		—	24	—		
Gate-drain ("Miller") charge	Q_{gd}		—	21	—		

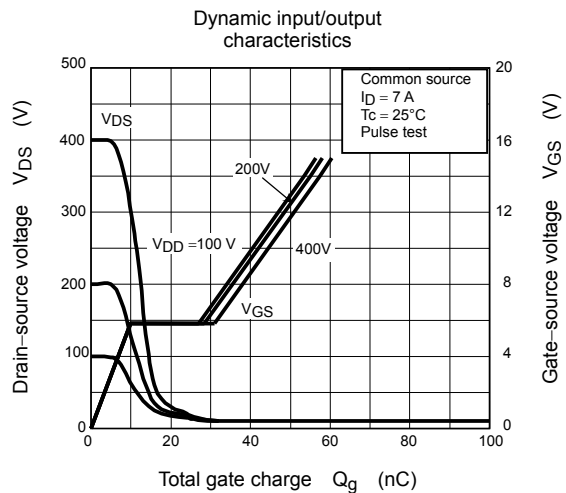
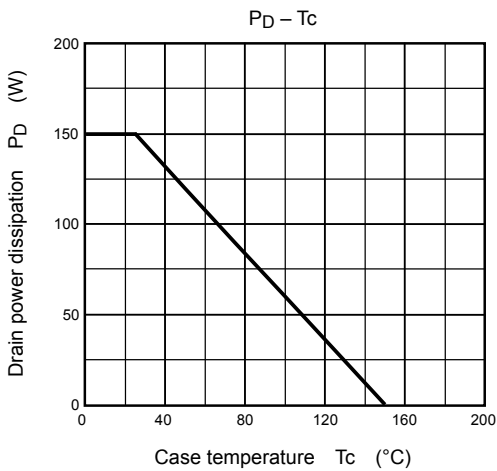
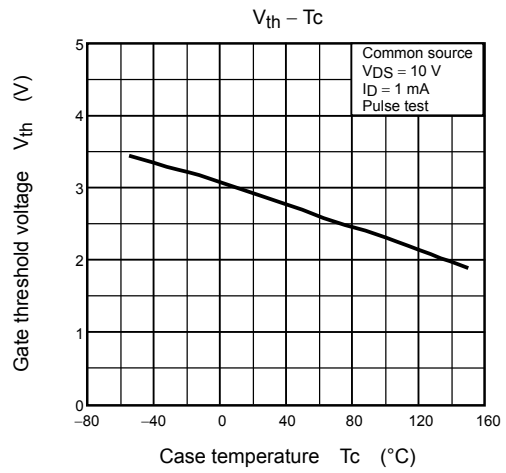
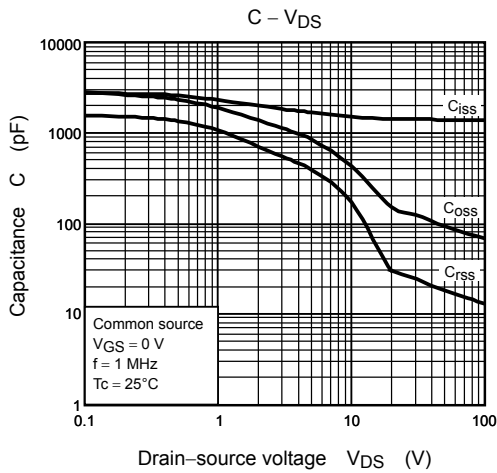
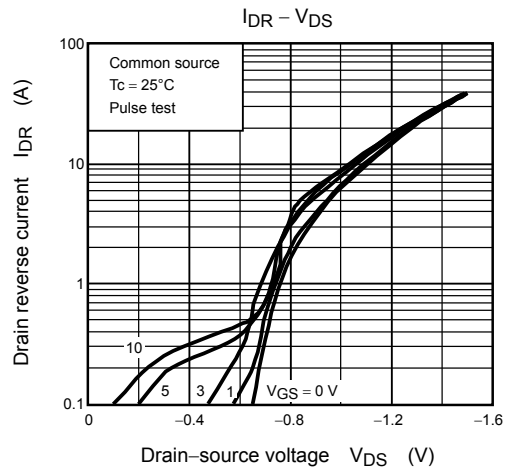
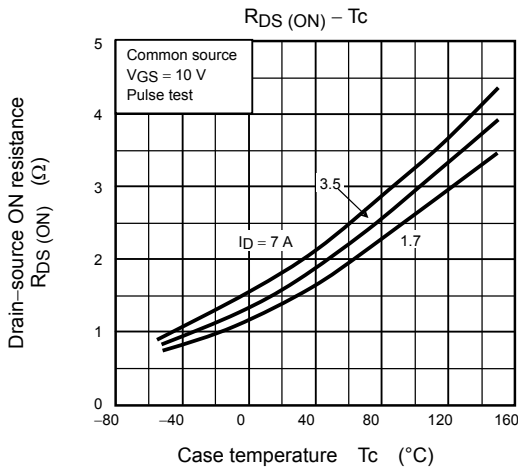
Source-Drain Ratings and Characteristics (Ta = 25°C)

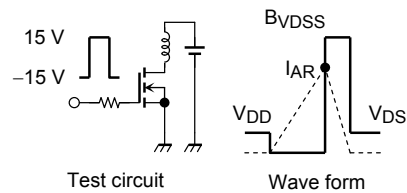
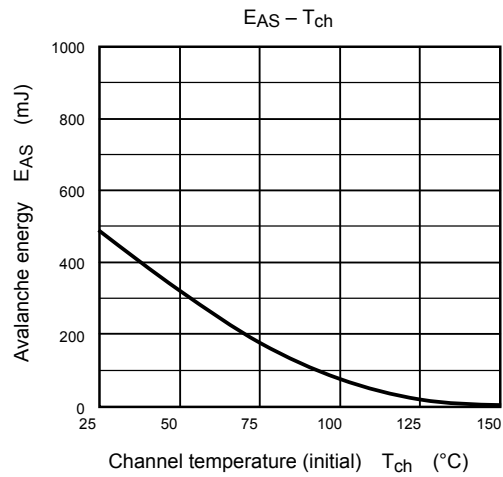
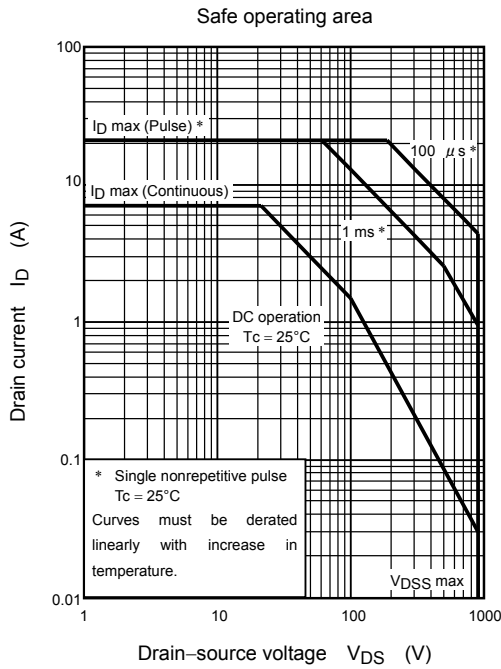
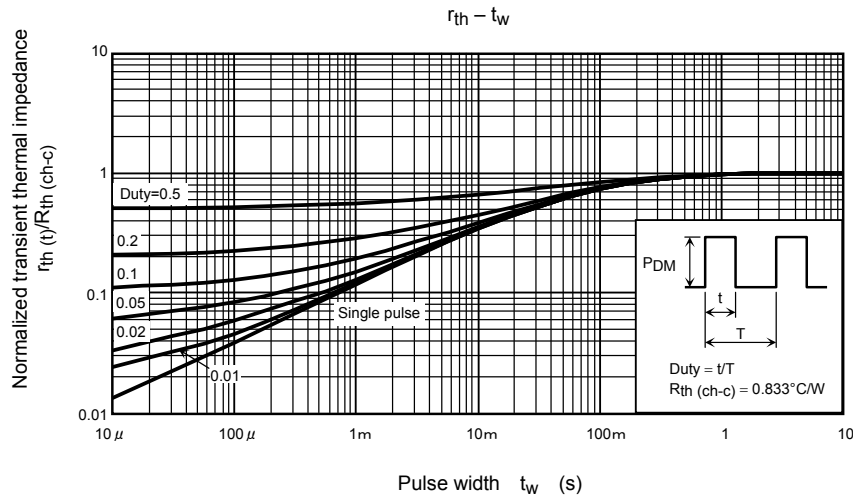
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	7	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	21	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 7\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.7	V
Reverse recovery time	t_{rr}	$I_{DR} = 7\text{ A}, V_{GS} = 0\text{ V}$	—	1400	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100\text{ A} / \mu\text{s}$	—	12	—	μC

Marking









$$R_G = 25 \Omega$$

$$V_{DD} = 90 \text{ V}, L = 18.4 \text{ mH}$$

$$EAS = \frac{1}{2} \cdot L \cdot I_{AR}^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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